

Electronic Patent Application Fee Transmittal

Application Number:	10710884			
Filing Date:	10-Aug-2004			
Title of Invention:	METHOD OF SOLDERING SEMICONDUCTOR PART AND MOUNTED STRUCTURE OF SEMICONDUCTOR PART			
First Named Inventor/Applicant Name:	Akihiro Mano			
Filer:	Larry Joe Hume			
Attorney Docket Number:	22040-00034-US1			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Independent claims in excess of 3	1201	1	200	200
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				200